



## Specification for Approval

- DEVICE NUMBER: BL-HJX39E
- CUSTOMER:

**SAMPLES  
ATTACHED AREA**

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2018/12/25	1.0	1.0	1.0	1.0	1.0	1.0	1.0				Original Released

### FOR CUSTOMER'S APPROVAL STAMP OR SIGNATURE

APPROVED	PURCHASE	MANUFACTURE	QUALITY	ENGINEERING

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 BRIGHT LED ELECTRONICS CORP.  
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ISSUED	APPROVED	PREPARED
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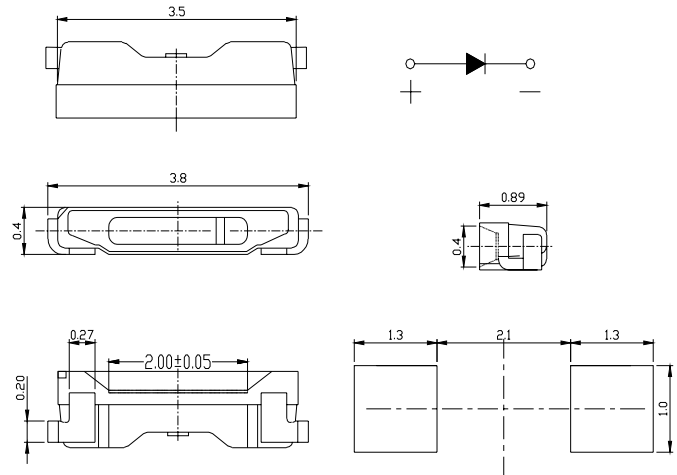
### ● Features:

1. Emitted Color : Spuer Red
2. Lens Appearance: Water Clear.
3. (3.8x0.4x0.89mm) standard package
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

### ● Applications:

1. Automotive : Dashboards, stop lamps, turn signals.
2. Backlighting : LCDs.
3. Status indicators : Consumer & industrial electronics.
4. General use.

### ● Package Dimensions:



#### NOTES:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.10\text{mm}$  ( $0.004''$ ) unless otherwise specified.
3. Specifications are subject to change without notice.

### ● Absolute Maximum Ratings( $T_a=25^\circ\text{C}$ )

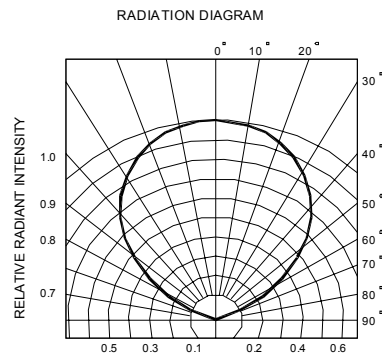
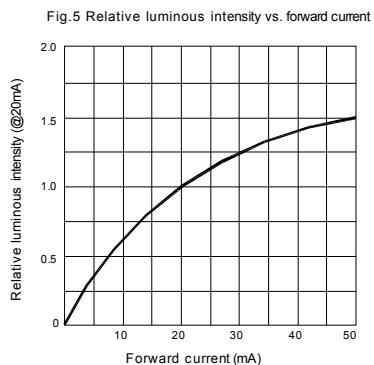
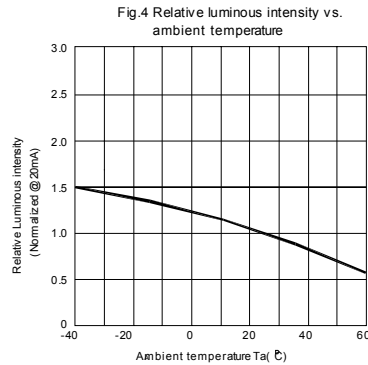
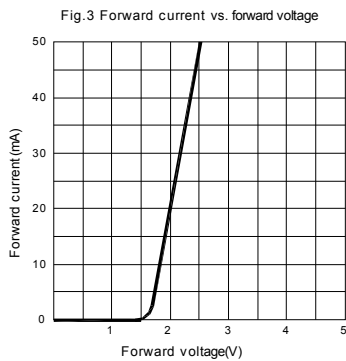
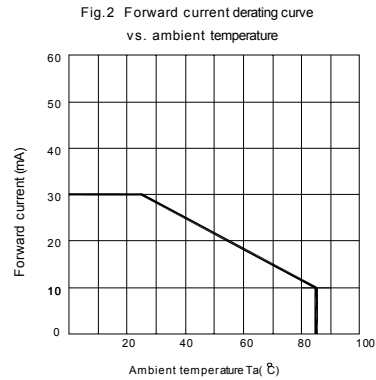
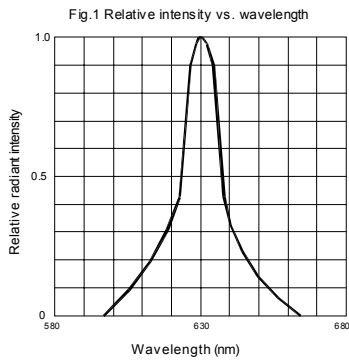
Parameter	Symbol	Rating	Unit
Power Dissipation	$P_d$	72	mW
Forward Current	$I_F$	30	mA
Peak Forward Current * 1	$I_{FP}$	100	mA
Reverse Volage	$V_R$	5	V
Operating Temperature	$T_{opr}$	-40~85	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40~100	$^\circ\text{C}$
Soldering Temperature	$T_{sol}$	See Page 6	-

\* 1 Condition for  $I_{FP}$  is pulse of 1/10 duty and 3 msec width.

### ● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V <sub>f</sub>	I <sub>F</sub> =20mA	-	2.0	2.4	V
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =20mA	-	700	-	mcd
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	-	-	10	μA
Peak Wave Length	λ <sub>p</sub>	I <sub>F</sub> =20mA	-	630	-	nm
Dominant Wave Length	λ <sub>d</sub>	I <sub>F</sub> =20mA	619		630	nm
Spectral Line Half-width	Δλ	I <sub>F</sub> =20mA	-	20	-	nm
Viewing Angle	2θ <sub>1/2</sub>	I <sub>F</sub> =20mA	-	105	-	deg

### ● Typical Electro-Optical Characteristics Curves



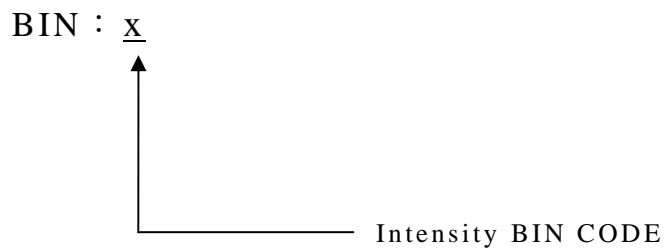


## ● Bin Limits

Intensity Bin Limits (At 20mA)

BIN CODE	Min. (mcd)	Max. (mcd)
U	475	715
V	715	1070
W	1070	1600

Tolerance for each Bin limit is  $\pm 15\%$ .



## ● Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
Endurance Test	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	Connect with a power $I_f=20\text{mA}$ $T_a$ =Under room temperature Test time=1,000hrs	0/20
	High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	$T_a=+65^\circ\text{C}\pm 5^\circ\text{C}$ RH=90%-95% Test time=240hrs	0/20
	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High $T_a=+85^\circ\text{C}\pm 5^\circ\text{C}$ Test time=1,000hrs	0/20
	Low Temperature Storage	JIS-C-7021 :B-12	Low $T_a=-35^\circ\text{C}\pm 5^\circ\text{C}$ Test time=1,000hrs	0/20
Environmental Test	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	$-35^\circ\text{C} \sim +25^\circ\text{C} \sim +85^\circ\text{C} \sim +25^\circ\text{C}$ 60min 20min 60min 20min Test Time=5cycle	0/20
	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	$-35^\circ\text{C}\pm 5^\circ\text{C} \sim +85^\circ\text{C}\pm 5^\circ\text{C}$ 20min 20min Test Time=10cycle	0/20
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS-C-7021 :A-1	Preheating : $140^\circ\text{C} - 160^\circ\text{C}$ , within 2 minutes. Operation heating : $260^\circ\text{C}$ (Max.), within 10seconds. (Max.)	0/20

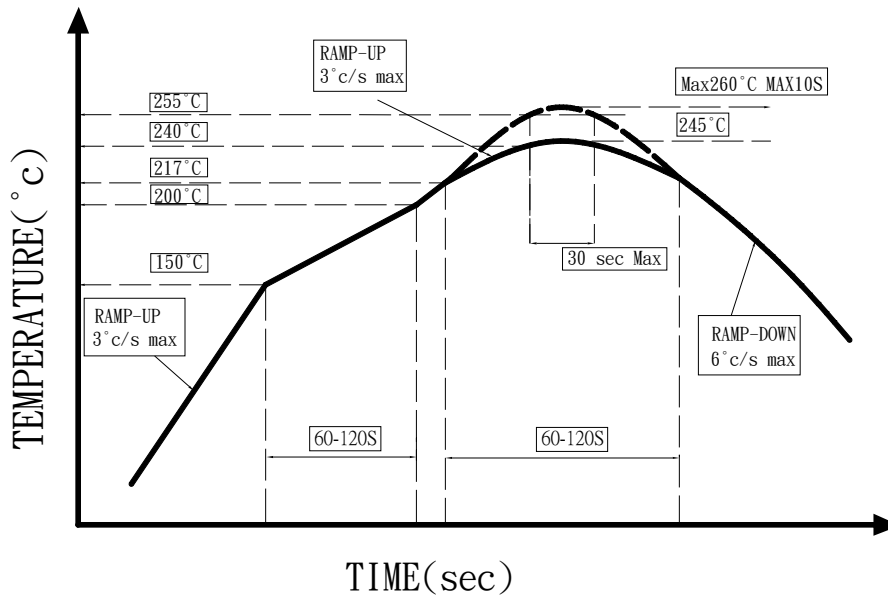
## ● Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgement criteria for failure
Forward voltage	$V_F$ ( V )	$I_F=20\text{mA}$	Over $U \times 1.2$
Reverse current	$I_R$ ( $\mu\text{A}$ )	$V_R=5\text{V}$	Over $U \times 2$
Luminous intensity	$I_v$ ( mcd )	$I_F=20\text{mA}$	Below $S \times 0.5$

Note: 1.U means the upper limit of specified characteristics. S means initial value.

2.Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.

## ● IR-Reflow Soldering



1. Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering .
2. Avoid rapid cooling or any excess vibration during temperature ramp-down process
3. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

## ● IRON Soldering

**350°C Within 3 sec, one time only.**

## ● Handling :

Care must be taken not to cause to the resin portion of BRIGHT LEDs while it is exposed to high temperature.

Care must be taken not rub the epoxy resin portion of BRIGHT LEDs with hard or sharp article such as the sand blast and the metal hook.

● **Notes for designing:**

Care must be taken to provide the current limiting resistor in the circuit so as to drive the BRIGHT LEDs within the rated figures. Also, caution should be taken not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as to be subjected to reverse voltage when turning off the BRIGHT LEDs.

● **Storage:**

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C (41°F) Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
  - a. Completed within 24hours.
  - b. Stored at less than 20% RH.
- (3) Devices require baking before mounting, if:
  - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:
  - 48 hours at 60°C±5°C.

● **Package and Label of Products:**

- (1) Package: Products are packed in one bag of 2000 pcs (one taping reel) and a label is attached on each bag.
- (2) Label:

